

# Approval Sheet for SMD LED

**Reference No** : S1608HM-012  
**Version No** : Rev 2  
**Customer Name** : Standard  
**Model Name** : LPAYG-LD10  
**Color** : Yellow-Green Color  
**Issued Date** : 22 May. 2006

## Customer


## Lasemtech

Develop.	Prod.	QA	Sales		Approved



*LASEMTECH INC.*

**358-1. Sin-Dong, Yungtong-Gu, Suwon-Si, Gyeonggi-Do, 442-390**  
**<http://www.lasemtech.com> Tel : (031) 205-0450., Fax : (031) 205-5315**



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

# 1. Features and Applications

- Package : SMD Package
- Resin : colorless clear type
- Dimensions in mm : 1.6 x 0.8 x 0.4 (L x W x H)
- Approx Weight : 0.88 mg
- Technology : AlInGaP Yellow-Green Color
- Viewing Angle : wide (120°)
- Assembly methods : suitable for all SMT assembly methods
- Soldering methods : IR reflow soldering
- Preconditioning : acc. to JEDEC Level 2a
- MSL : Qualified according to JEDEC moisture sensitivity Level 2a.
- Taping : 8mm conductive black carrier tape & antistatic clear cover tape  
4,000pcs/reel, Φ180mm wheel
- ESD-withstand voltage : Class 2 acc. to JESD22-A114-C
- RoHs : Environmental friendly, RoHS compliance.

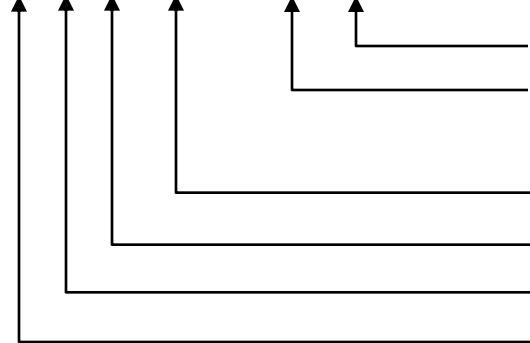
## Applications:

- Outdoor displays
- Backlighting (LCD, switches, keys, displays, illuminated advertising, general lighting)
- Interior automotive lighting (e.g. dashboard backlighting, etc.)
- Indicator

# 2. Part Name Description



L P A YG - LD 10



10 : Specification **Rev. No. (optional)**

LD : Specification **Code No. (optional)**

YG : **Yellow-Green** color

A : **1.6mm x 0.8mm** Series

P : PCB Type SMD LED

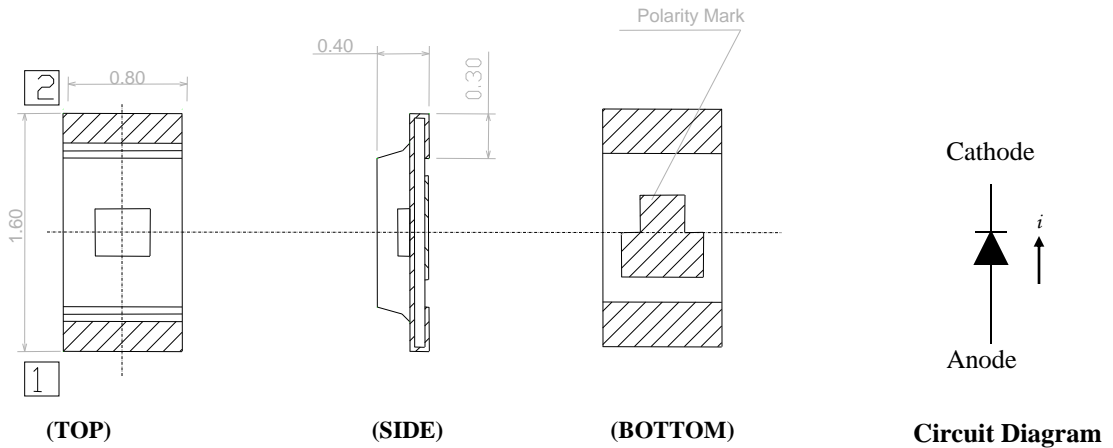
L : Company Name, **LASEMTECH. INC.**



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

### 3. Outline Dimensions and Materials

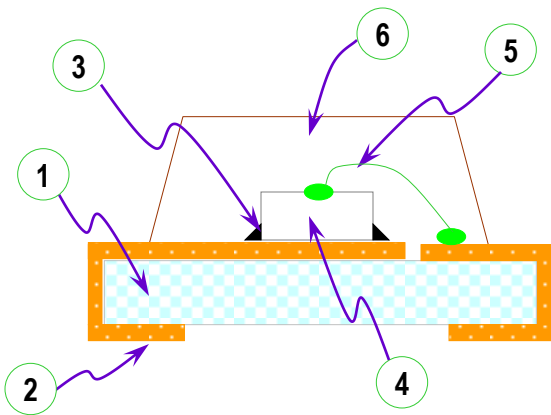
#### 1) Outline Dimensions



- MODEL : LPAYG
- TYPE : 1.6 x 0.8 x 0.4 (t)
- TOLERANCE : ± 0.10 mm

#### 2) Materials

- Package : Epoxy Resin , Clear (Optional : Diffuser type)
  - Paste : Silver filled Epoxy
  - Electrode : Au Plating
- Surface Treatment of Terminals : Au Plating



Number	Item	Material
1	PCB	BT Resin
2	Lead	Cu / Au
3	Paste	Ag Paste
4	LED Chip	AllnGaP / GaAs
5	Wire	Gold Wire
6	Compound	Clear Compound



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#/ 13

## 4. Specifications

### 1) Absolute Maximum Ratings

Items	Symbol	Maximum Rating	Unit
Forward Current	$I_F$	20	mA
Pulse Forward Current*	$I_{FP}$	100	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_D$	45	mW
Operating Temperature	$T_{opr}$	- 30 ~ 80	°C
Storage Temperature	$T_{stg}$	- 40 ~ 85	°C

$T_a = 25\text{ °C}$

$I_{FP}$  Conditions : Pulse Width  $\leq 0.1$  msec. And Duty  $\leq 1/10$

### △ 2) Initial Electrical / Optical Characteristics

Items	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	$V_F$	1.90	-	2.20		$I_F = 20\text{ mA}$
Luminous Intensity	$I_v$	30	-	70		$I_F = 20\text{ mA}$
Dominant Wavelength	Wd	568.5	-	572.5	-	$I_F = 20\text{ mA}$
Full Width at Half Maximum	$\Delta\lambda$	-	20	-	nm	$I_F = 20\text{ mA}$
Viewing Angle	$2\theta_{1/2}$	-	120	-	Deg.	$I_F = 20\text{ mA}$

Luminous Intensity Measuring Equipment : LX4560A (Teknologue, JAPAN)

Voltages are tested at a current pulse duration 1ms and an accuracy of  $\pm 0.1V$

Luminous Intensity is tested at a current pulse duration 5ms and an accuracy of  $\pm 10\%$

Dominant Wavelength is tested at a current pulse duration 5ms and an accuracy of  $\pm 1\text{ nm}$



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

## 5. Grouping parameter

### 1) Dominant Wavelength Ranks

$W_D$ Rank	Min	Typ	Max	Unit	Test Condition
B	568.5	-	569.5	nm	$I_F = 20 \text{ mA}$
C	569.5		570.5		

Dominant Wavelength is tested at a current pulse duration 5ms and an accuracy of  $\pm 1 \text{ nm}$

### 2) Forward Voltage

( $T_a = 25 \text{ }^\circ\text{C}$ )

$V_F$ Rank	Min	Typ	Max	Unit	Test Condition
B	1.90	-	2.00	V	$I_F = 20 \text{ mA}$
C	2.00		2.10		
D	2.10	-	2.20		

Voltages are tested at a current pulse duration 1ms and an accuracy of  $\pm 0.1 \text{ V}$

### 3) Luminous Intensity Ranks

( $T_a = 25 \text{ }^\circ\text{C}$ )

$I_V$ Rank	Min	Typ	Max	Unit	Test Condition
B	30	-	40	mcd	$I_F = 20 \text{ mA}$
C	40	-	50		
D	50	-	60		
E	60	-	70		

Luminous Intensity is tested at a current pulse duration 5ms and an accuracy of  $\pm 10\%$



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

## 6. Typical Characteristic Curve

Fig.1 Maximum forward current vs. temperature

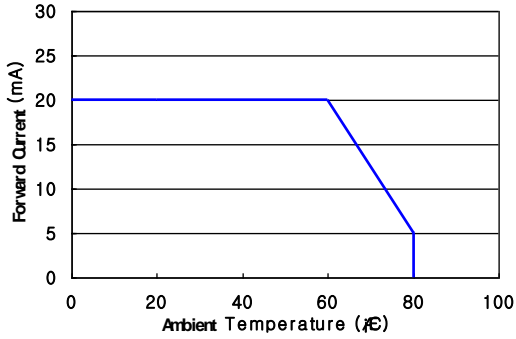


Fig.2 Forward current vs. Luminous Intensity

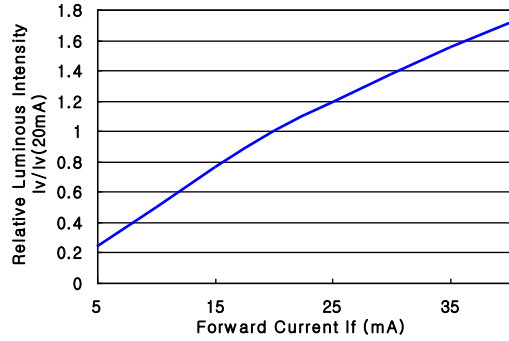


Fig.3 Wavelength Distribution

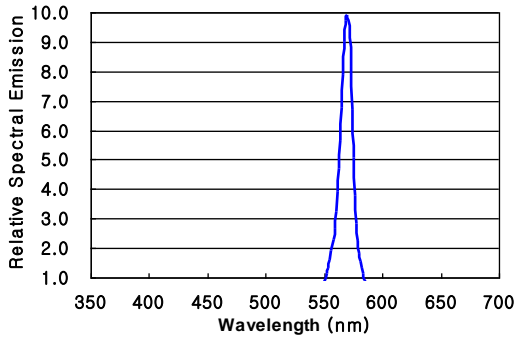


Fig.4 Forward voltage vs. Forward current

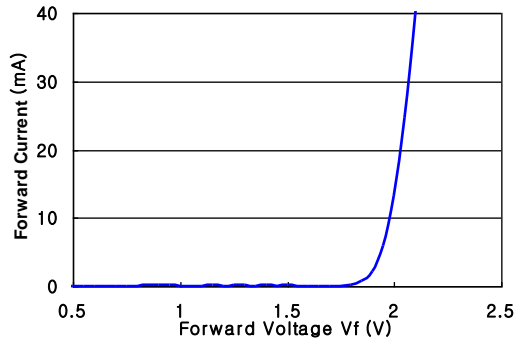


Fig.5 Dominant Wavelength

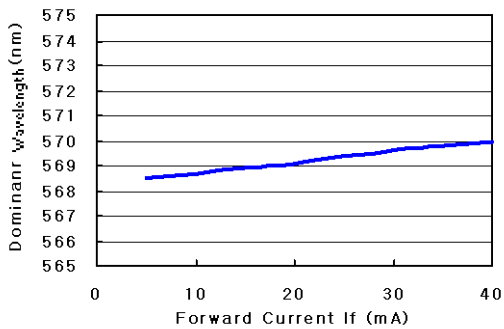
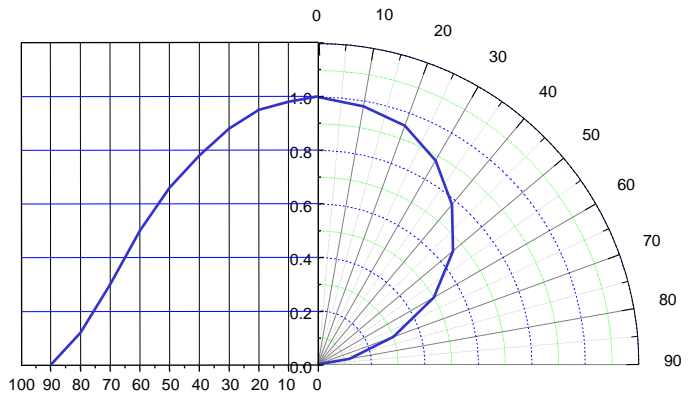


Fig.6 Radiation Diagram



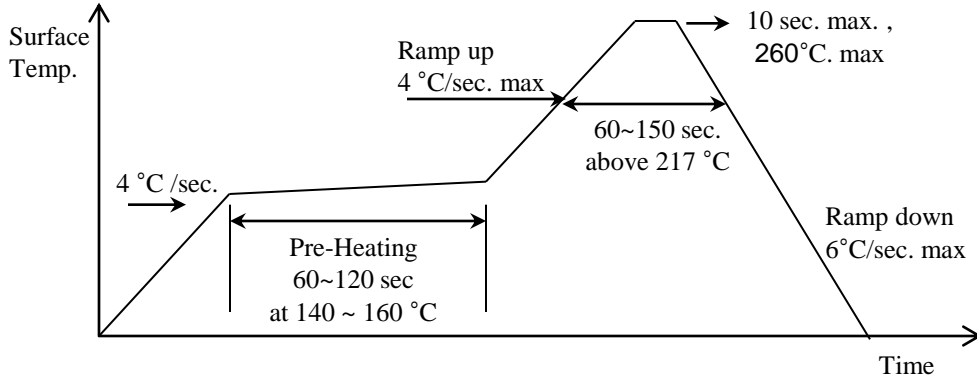


Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

## 7. Soldering Conditions

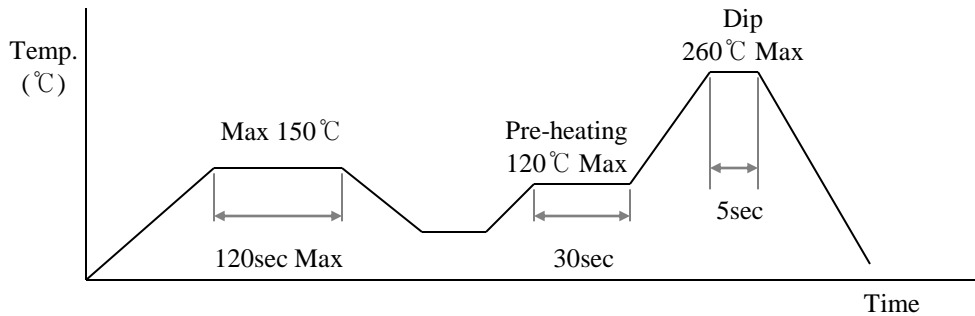
Reflow soldering is recommended , and soldering should not be done more than two times. When repairing is done , a double-headed soldering iron should be used.

### 1) Lead-free Solder Re-flow Profile (JEDEC J-STD-020C).



### 2) Solder Dip Profile

The Immersion of leads into a solder bath @MAX260 °C shall be to 5 seconds max.



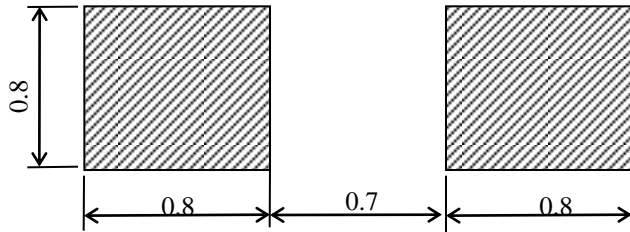
### 3) For manual solder

Not more than 5sec @max 300°C, under soldering iron.



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

#### 4) Recommendable Soldering Pattern



#### 5) Precaution When Mounting

Do not apply force to the plastic part of the LED under high-temperature conditions.  
To avoid damaging the LED plastic do not apply friction using hard materials.  
When installing the PCB in product, ensure that the device does not come into contact with other components

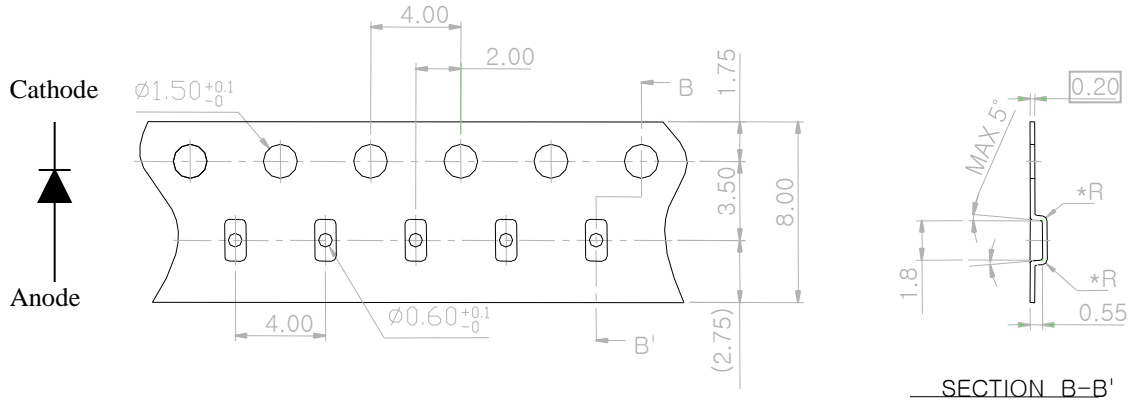




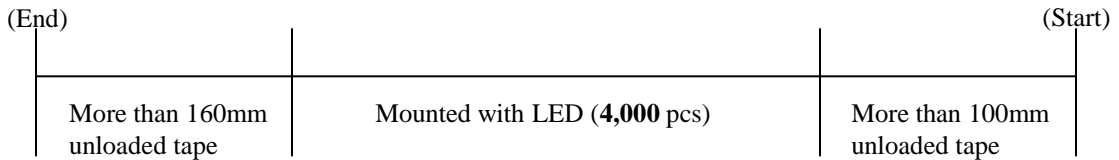
Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

## 8. Packing Process and Materials

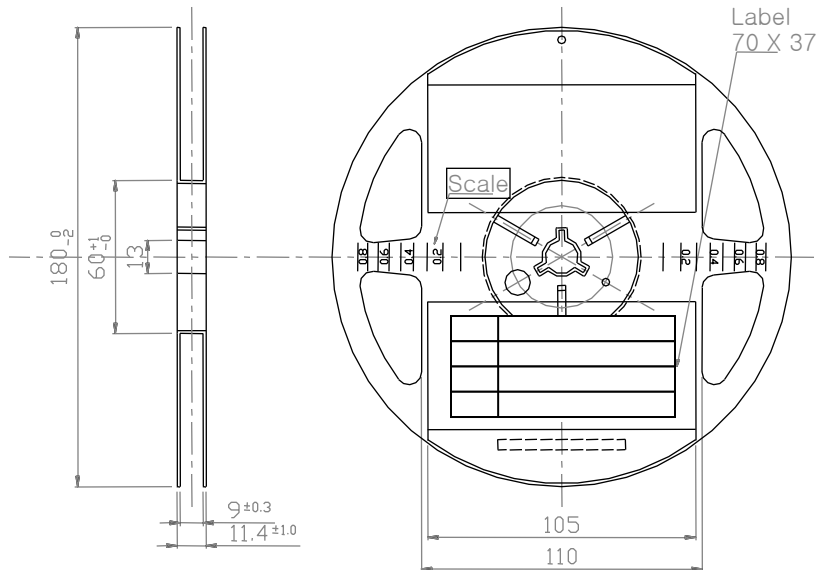
### 1) Dimension of tape(Material : PS Conductive, 10E4~5Ω)



### 2) Details of Chip LEDs loading on tape

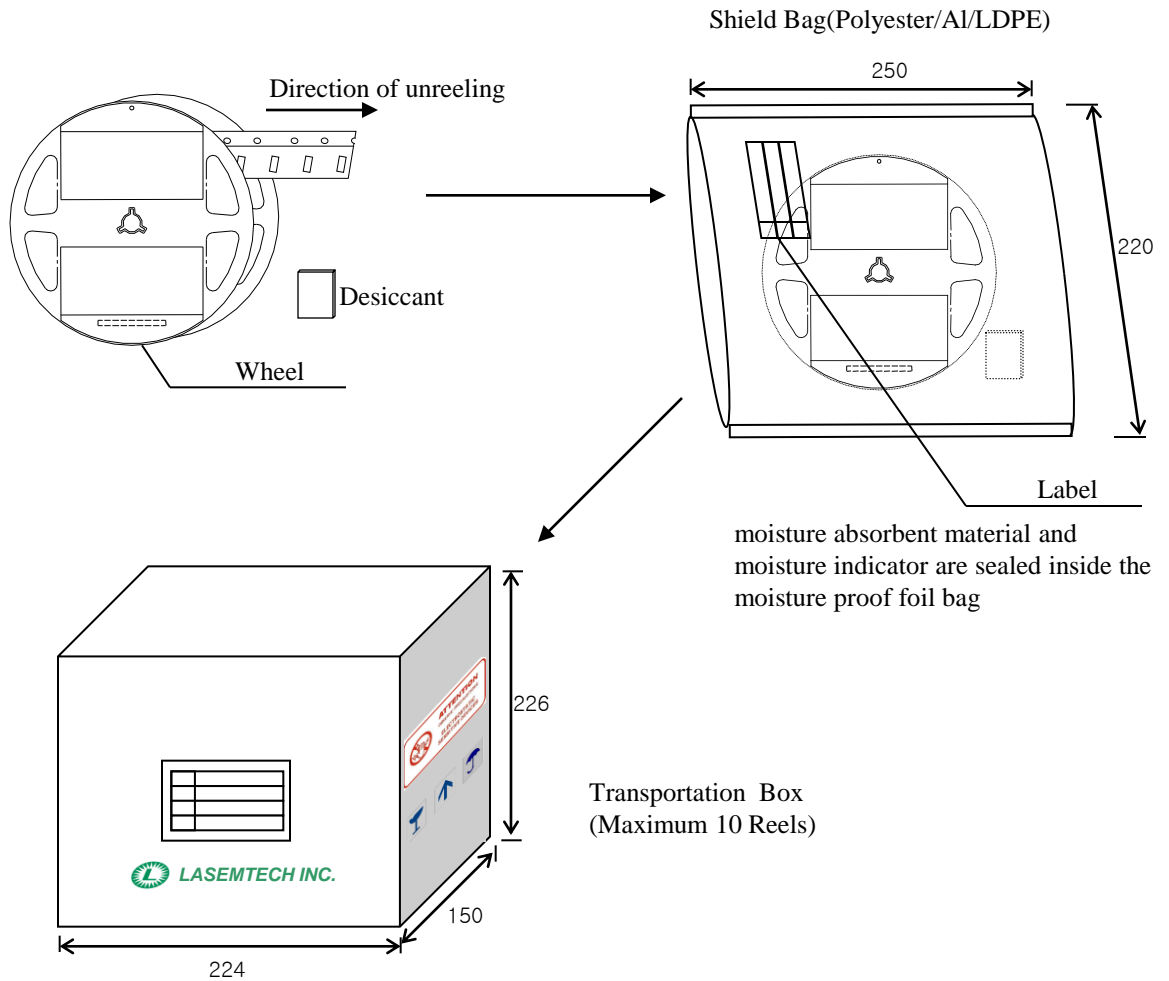


### 3) Dimension of Reel(Material : PS Conductive, 10E9~12Ω)

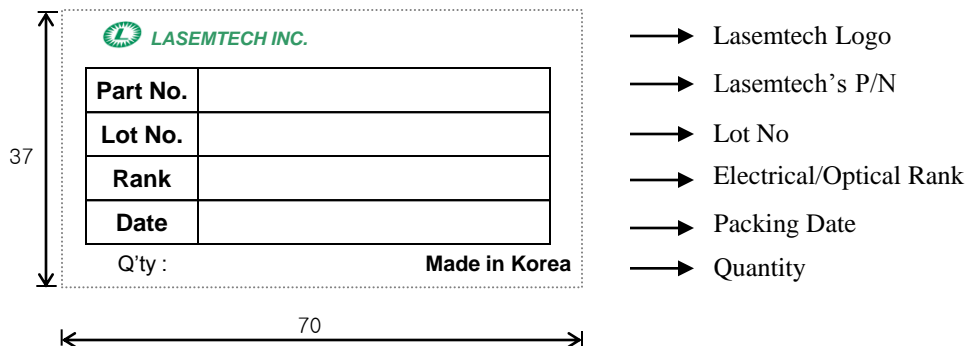


- (1) Quantity : Product are packed in one taping reel of max. **4,000** pcs.
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be  $\pm 0.2$ mm
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at  $10^\circ$  angle to be the carrier tape.
- (4) Packaging : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package.

#### 4) Packing Structure



#### 5) Labeling





Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

## 9. Reliability

### 1) The reliability Criteria of SMD LED

Items	Symbol	Test Conditions	Criteria for Judgement	
			Min.	Max.
Forward Voltage	$V_F$	$I_F=5\text{mA}$	-	U.S.L.*) $\times 1.1$
Reverse Current	$I_R$	$V_R = 5\text{ V}$	-	20uA
Luminous Intensity	$I_V$	$I_F=5\text{mA}$	L.S.L.**) $\times 0.7$	-

□ \*) U.S.L. : Upper Standard Level

\*\*\*) L.S.L. : Lower Standard Level

### 2) Results of reliability test

Test Items	Reference	Test Conditions	Note
High Temperature Storage	JEITA ED-4701 200 201	85 °C / 1,000 hr.	0/32
Low Temperature Storage	JEITA ED-4701 200 202	-40 °C / 1,000 hr.	0/32
Temp. Humidity Storage	JEITA ED-4701 100 103	60 °C / 90 % RH / 1,000 hr.	0/32
Steady State Operating Life	EIA/JESD 22- A108-B	25 °C / 20 mA / 1,000 hr.	0/32
High Temperature Operating Life	EIA/JESD 22- A108-B	80 °C / 5 mA / 1,000 hr.	0/32
Low Temperature Operating Life	EIA/JESD 22- A108-B	-30 °C / 20 mA / 1,000 hr.	0/32
Steady State Operating life of High Humidity Heat	JEITA ED-4701 100 102	60 °C / 90 % RH / 10 mA 1,000 hr.	0/32
Temperature Cycle	JEITA ED-4701 100 105	-40°C(30min) → 25(5min.) → 100(30min.) / 100 cycle	0/22



Spec No.	Ver.	Date	Page
S1608HM-012	2	2006/05/22	<#>/ 13

## 10. Precaution for use

- This device should not be used in any type of fluid such as water, oil, organic solvent, etc.  
When washing is required, IPA should be used.
- When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- LEDs must be stored to maintain a clean atmosphere.  
If the LEDs are stored for 3months or more after being shipped from LASEMTECH, a sealed container with a nitrogen atmosphere should be used for storage.
- After opening the moisture proof packing, the LED's should be kept at 5°C~30°C, 60%RH or below.  
The LEDs must be soldered within seven days(168 hours) after opening the moisture-proof packing.  
If the LEDs remains after soldering, it should be stored into moisture proof container.
- Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.
- If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the device should be baked in taping with reel using the conditions of 65±5°C, 12~24hours.  
After baking, use the baked devices within 72hours, but perform baking only once.
- Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
- The appearance and specifications of the product may be modified for improvement without notice.
- If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices..
- This LEDs is sensitive to the electrostatic and surge,  
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- If over-voltage which exceeds the absolute maximum rating is applied to LEDs, It will cause damage LEDs and result in destruction.
- Damaged LEDs will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LEDs get unlight at low current.
- It is better not to use different rank LEDs.  
If use mixed rank, could not attain your object for highest quality of products.